

Raytheon Systems Limited

This document is an integral part of the contract (purchase order) which calls it out.
The revision in effect at the time the purchase order was placed applies.

I007B, Rev 1

(17/07/06)

SOLDERABILITY

Hybrids Only. On receipt, it shall be verified that these components have been subjected to the following solderability testing requirements:

Packages will be temperature aged to one of the following Conditions prior to performing the solderability test.

6+/-0.5 hours at $T_a = +250^{\circ}\text{C}$, +/-10°C

22+/-1 hour at $T_a = +200^{\circ}\text{C}$, +/-8°C

160+/-8 hours at $T_a = +150^{\circ}\text{C}$, +/-6°C

When the device process flow includes an operation in which the package lead finish is changed prior to delivery of the device (i.e. a solder coating is applied), this operation will be performed on the package evaluation sample packages subsequent to the temperature aging. Following the temperature aging (and the lead finish application, if applicable), the sample packages will be solderability tested in accordance with Mil-Std-883 method 2003 including an 8 hour (+/- 0.5 hour) steam aging.